

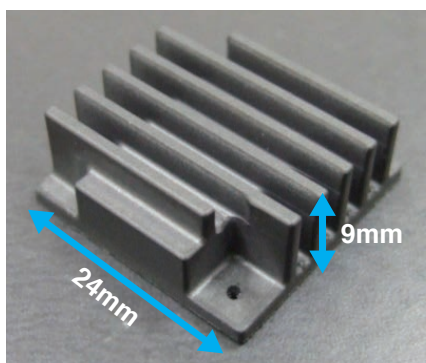
VA suggestion by UNX7007

High thermal conductive / High strength / EMI shield polymer

Characteristics and Advantages

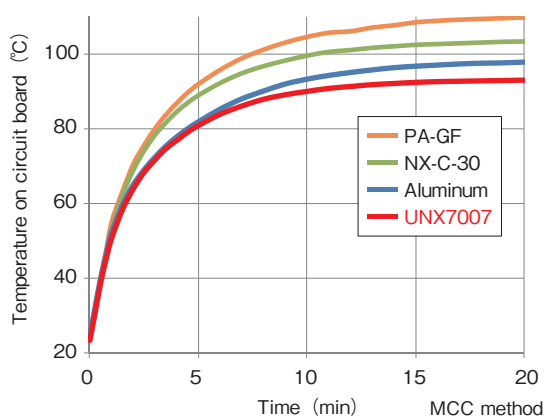
- High thermal conductivity
- High strength
- EMI shield

Heat radiation test



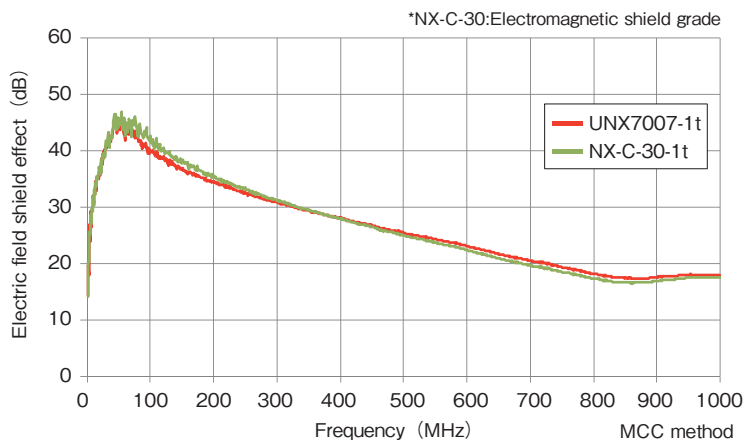
- Front cover : High thermal conductivity materials.
- Back cover : PA-GF
- Temperature measurement point : Near the circuit in the cover.
- The electric power : 1.4W

Temperature on circuit board with various covers



*)All technical information and data are typical values, and are not standard values.

EMI shield



Applicable components

- Development of cover for heat radiation

Proposal for the future

- Aluminum die casting → Reduction of the secondary process cost
- Conventional thermal conductive polymer → Reduction of the parts
- Conventional polymer → Corresponding of high speed IC